# GL514/GL513F

#### **■** Features

1. Output : **GL514**  $\Phi_e$  MIN. 3.31mW at

 $I_F = 100 \text{mA}$ 

**GL513F**  $\Phi$  e MIN. 1.44mW at

 $I_F = 100 \text{mA}$ 

2. Beam angle : **GL514**  $\Delta\theta$  : TYP.  $\pm$  7°

**GL513F**  $\Delta\theta$  : TYP.  $\pm$  50°

3. To- 18 type standard package

4. High reliability, long operation life

# ■ Applications

1. Optoelectronic switches

2. Smoke detectors

3. Infrared applied systems

### **■** Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$ 

Parameter	Symbol	Rating	Unit
Power dissipation	P	250	mW
Forward current	$I_F$	150	mA
*1Peak forward current	$I_{FM}$	2	A
Reverse voltage	V <sub>R</sub>	6	V
Operating temperature	T opr	- 40 to + 125	°C
Storage temperature	T stg	- 55 to + 125	°C
*2Soldering temperature	T sol	260	°C

<sup>\*1</sup> Pulse width $\leq$ = 200  $\mu$ s

Duty ratio = 0.01

# **■** Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$ 

Parameter Symbol Conditions		Conditions	MIN.	TYP.	MAX.	Unit	
Forward voltage		VF	$I_F = 100 \text{mA}$	-	1.35	1.6	V
Peak forward voltag	Voltage $V_{FM}$ $I_{FM} = 1.5A$		$I_{FM} = 1.5A$	-	2.75	4.0	V
Reverse current		$I_R$	$V_R = 5V$	-	-	100	μΑ
Terminal capacitance		Ct	V = 0, $f = 1MHz$	-	70	-	pF
*3Radiant flux	GL514	Α	I 100 A	3.31	5.35	10.0	mW
Radiant flux	GL513F	Фе	$I_F = 100 \text{mA}$		2.88	-	mW
Peak emission wave	length	$\lambda_p$ $I_F = 100 \text{mA}$		-	950	-	nm
Half intensity wavelength $\Delta \lambda$ I <sub>F</sub> = 100mA		-	45	-	nm		

# TO-18 Type Infrared Emitting Diode

**■** Outline Dimensions

(Unit: mm)

GL514	GL513F
Glass lens_	
6L514	φ 4.7 <sup>±</sup> 0.1 φ 3 GL513F SHARP  (C) (C) (D) (D) (D) (D) (D) (D) (D) (D) (D) (D
φ 5.7 <sup>MAX.</sup>	φ 5.7 <sup>MAX</sup> .
<b>`</b>	① Cathode
	② Anode

<sup>\*2</sup> For 10 seconds at the position of 1.3mm from the bottom face of can package.

#### \*3 Classification Table of Radiant Flux

Model No.	Rank Mark	Φ <sub>e</sub> (mW)	
GL514A	A	5.35 to 10.0	
GL514	-	3.31 to 10.0	

at  $I_F = 100 \text{mA}$ ,  $Ta = 25^{\circ}\text{C}$ 

Fig. 1 Forward Current vs.

Ambient Temperature

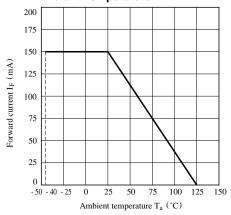


Fig. 3 Spectral Distribution

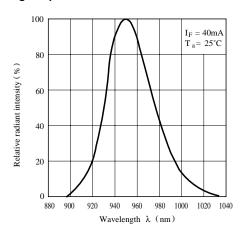


Fig. 2 Peak Forward Current vs. Duty Ratio

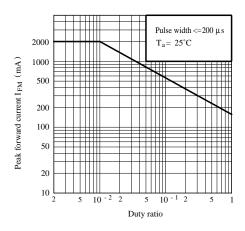


Fig. 4 Peak Emission Wavelength vs.
Ambient Temperature

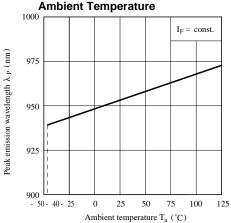


Fig. 5 Forward Current vs. Forward Voltage

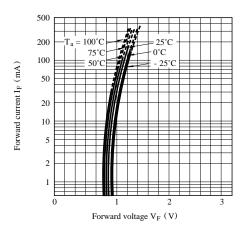


Fig. 7 Radiant Flux vs.
Forward Current (GL514)

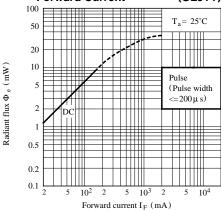


Fig. 9 Relative Radiant Intensity vs.
Distance (GL514)

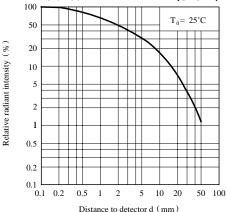


Fig. 6 Relative Radiant Flux vs.
Ambient Temperature

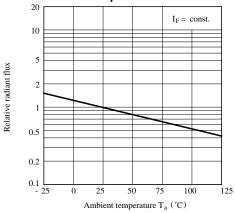


Fig. 8 Radiant Flux vs.

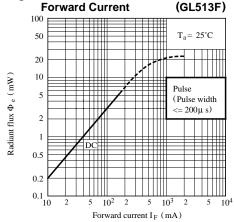


Fig.10 Relative Radiant Intensity vs.

Distance (GL513

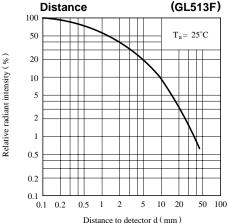
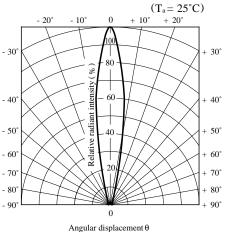




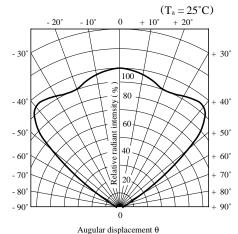
Fig.11 Radiation Diagram



(GL514)

Fig.12 Radiation Diagram

(GL513F)



• Please refer to the chapter "Precautions for Use."

#### **NOTICE**

- •The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.
- •Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:
  - (i) The devices in this publication are designed for use in general electronic equipment designs such as:
  - Personal computers
  - Office automation equipment
  - Telecommunication equipment [terminal]
  - Test and measurement equipment
  - Industrial control
  - Audio visual equipment
  - Consumer electronics
  - (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
  - Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
  - Traffic signals
  - Gas leakage sensor breakers
  - Alarm equipment
  - Various safety devices, etc.
  - (iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
  - Space applications
  - Telecommunication equipment [trunk lines]
  - Nuclear power control equipment
  - Medical and other life support equipment (e.g., scuba).
- •Contact a SHARP representative in advance when intending to use SHARP devices for any "specific" applications other than those recommended by SHARP or when it is unclear which category mentioned above controls the intended use.
- •If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Control Law of Japan, it is necessary to obtain approval to export such SHARP devices.
- •This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.
- Contact and consult with a SHARP representative if there are any questions about the contents of this
  publication.